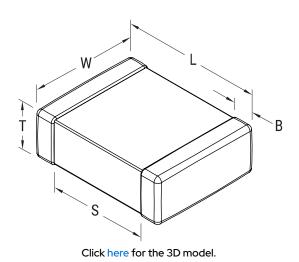




SMD Comm X8G HT150C, Ceramic, 1,100 pF, 1%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1812, 2.3 mm



General Information		
Series	SMD Comm X8G HT150C	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Tin	
Marking	No	
AEC-Q200	No	
Typical Component Weight	67 mg	
Shelf Life	78 Weeks	
MSL	1	

1,100 pF

Dimensions	
Chip Size	1812
L	4.5mm +/-0.3mm
W	3.2mm +/-0.3mm
Т	1mm +/-0.10mm
S	2.3mm MIN
В	0.6mm +/-0.35mm

••	0.2 / 0.0
Т	1mm +/-0.10mm
S	2.3mm MIN
В	0.6mm +/-0.35mm
Packaging Specifications	

Packaging

Packaging Quantity

4.5mm +/-0.3mm	Measure	ement Condition	1 kHz 1.0Vrms	
3.2mm +/-0.3mm	Toleran	ce	1%	
1mm +/-0.10mm	Voltage	DC	200 VDC	
2.3mm MIN	Dielectr	ric Withstanding Voltage	500 VDC	
0.6mm +/-0.35m	m Temper	ature Range	-55/+150°C	
	Temp. C	Coefficient	X8G	
ations		ance Change with	30 ppm/C, 1kHz 1.0Vrms	
T&R, 330mm, Pla	stic Tape Reteren Applied	ice to +25°C and 0 VDC (TCC)		
4000	Dissipat	tion Factor	0.1% 1 kHz 1.0Vrms	
	Aging R	ate	0% Loss/Decade Hour: Referee Time is 1000 Hours	
	Insulatio	on Resistance	100 GOhms	

Specifications

Capacitance

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and
we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the
requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us
with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

© 2006 - 2025 YAGEO Generated 05/03/2025